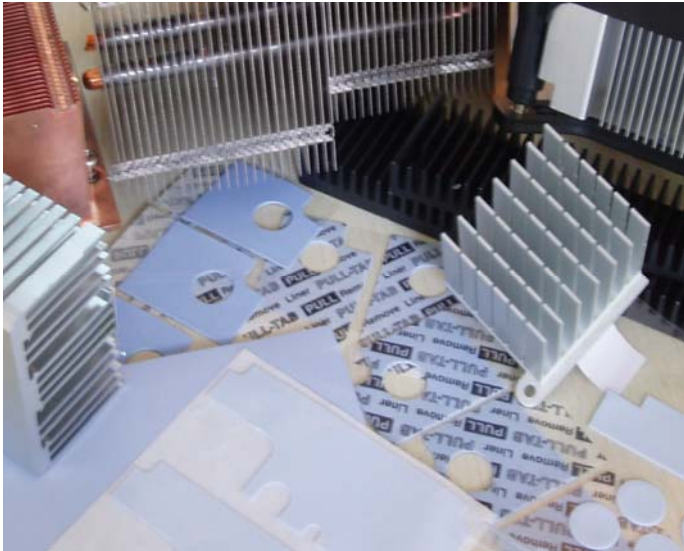


Thermal Conductive Gap Fillers



TIF600 series offers excellent thermal performance and high compression set while remaining cost effective. This material conforms to surface irregularities under low application pressures to fill air gaps between components and the heat source.

TIF600 series combines good thermal conductivity of 4.7W/mK with high compressibility to produce low thermal resistance. TIF600 series is electrically non-conductivity, stable from -50°C to 200°C. The material is naturally tacky. Additional adhesive coating is not required.

◆ Features and Benefits

- 4.7W/mK thermal conductivity
- Highly compressible and cost effective
- Naturally tacky
- Electrically Isolating

◆ Typical Applications

- Cooling Components to the Chassis, Frame, or other type of heat spreader
- Mass Storage Drives
- Heat Pipe assemblies
- RDRAM Memory Modules
- Motor Control
- Telecommunication Hardware

Typical Properties of TIF600 series

Product Name	TIF600	Test Method
Color	Blue - Violet	Visual
Construction & Composition	Ceramic filled silicone elastomer	***
Thickness (inch/mm)	0.010 to 0.200 inch 0.254 to 5.08mm	ASTM D751
Specific Gravity, (g/cc)	2.8	ASTM D297
Heat Capacity, (J/g-K)	1.0	ASTM C351
Hardness, (Shore A)	30	ASTM 2240
Tensile Strength, (psi)	55	ASTM D412
Continuous Use Temp, (°F/°C)	(-58 to 392°F) (-50 to 200°C)	***
Electrical		
Dielectric Breakdown Voltage, (VAC)	>3500	ASTM D149
Dielectric Constant, (1000 Hz)	7.5	ASTM D150
Volume Resistivity, (Ohm-meter)	7.8X10 ¹⁰	ASTM D257
Flame Rating	94 V0	equivalent UL
Thermal		
Thermal Conductivity, (W/m-K)	4.7	ASTM D5470